

## Jahresbericht 2023

# TK 47, Halbleiterbauelemente

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Im Berichtsjahr fand keine Sitzung des TK 47 statt. Insgesamt wurden 151 Dokumente aus IEC an das TK verteilt. Die 54 Stellungnahmen erfolgten auf dem Korrespondenzweg. Das TK besteht aktuell aus 8 Mitgliedern.

Im Jahr 2023 wurden folgende Normen publiziert:

- SN EN IEC 60747-16-7:2023 "Semiconductor devices - Part 16-7: Microwave integrated circuits – Attenuators"
- SN EN IEC 60747-16-8:2023 "Semiconductor devices - Part 16-8: Microwave integrated circuits – Limiters"
- SN EN IEC 63364-1:2023 "Semiconductor devices - Semiconductor devices for IoT system - Part 1: Test method of sound variation Detection"
- SN EN IEC 62951-8:2023 "Semiconductor devices - Flexible and stretchable semiconductor devices - Part 8: Test method for stretchability, flexibility, and stability of flexible resistive memory"
- IEC 60747-18-4:2023 "Semiconductor devices - Part 18-4: Semiconductor bio sensors - Evaluation method of noise characteristics of lens-free CMOS photonic array sensors"
- IEC 60747-18-5:2023 "Semiconductor devices - Part 18-5: Semiconductor bio sensors - Evaluation method for light responsivity characteristics of lens-free CMOS photonic array sensor package modules by incident angle of light"
- IEC 60747-5-16:2023 "Semiconductor devices - Part 5-16: Optoelectronic devices - Light emitting diodes - Test method of the flat-band voltage of GaN-based light emitting diodes based on the photocurrent spectroscopy"
- SN EN IEC 63287-2:2023 "Semiconductor devices - Guidelines for reliability qualification plans - Part 2: Concept of mission profile"
- IEC 61967-8:2023 "Integrated circuits - Measurement of electromagnetic emissions - Part 8: Measurement of radiated emissions - IC stripline method"

Das TK 47 ist aktuell mit 3 Experten in 4 internationalen Arbeitsgruppen vertreten.

(D. D.)